# **PRODUCT SPECIFICATION**

# CS2004C-D-BSXTSWN-190

V1.0

April 2, 2009





REV	Description	Date
V1.0	First Release	April 2, 2009

# **REVISION RECORD**



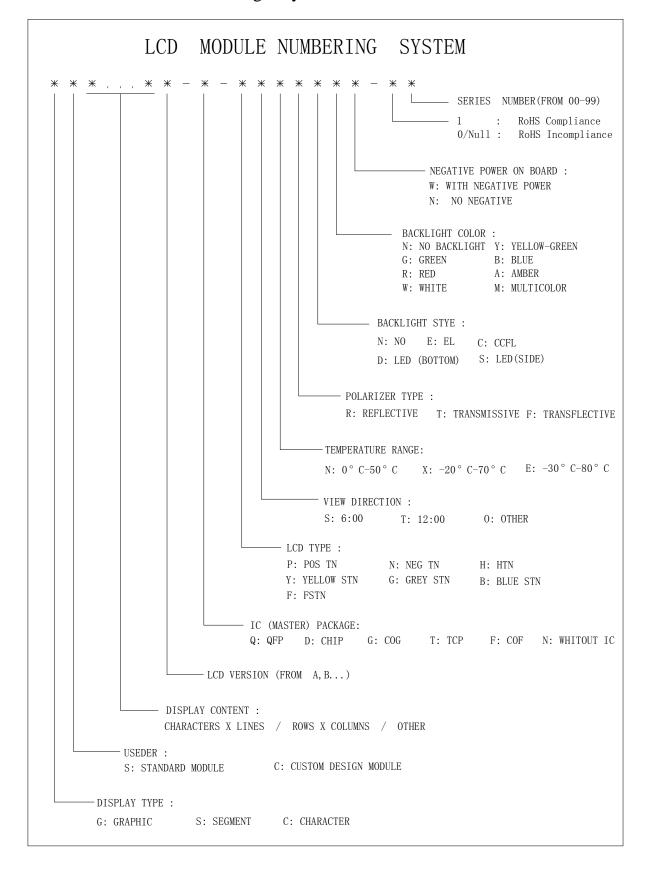
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1. Type Number And Description

Type Number	:	CS2004C-D-BSXTSWN-190
Description	:	20Characters X 4Lines
LCD Panel	:	Blue STN, Negative, Transmissive
Viewing angle	:	6H
Duty	:	1/16
Bias	:	1/5
Operating Temperatu	re:	$-20^{\circ}C - 70^{\circ}C$
Storage Temperature	:	$-30^{\circ}C - 80^{\circ}C$
Controller	:	ST7066U-OB Or Equivalent
IC package	:	Bonding
BackLight	•	White LED, Side



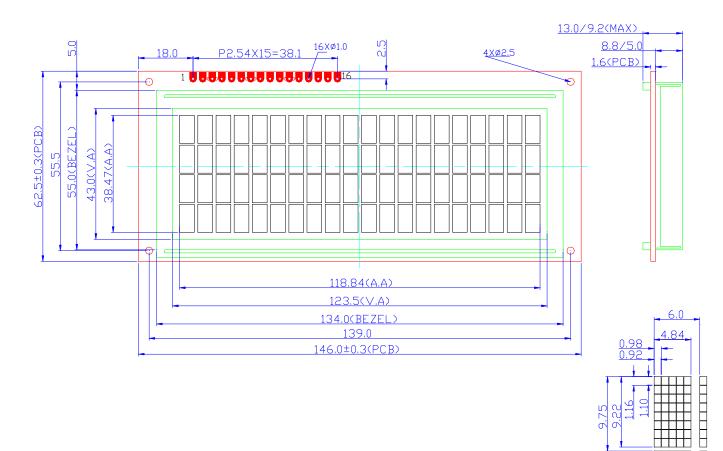


#### 2. LCD Module Numbering System



ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	20 CHARACTERS X 4LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	146.0(W) X 62.5(H) X 13.0(T)	mm
EFFECTTVE DISPLAY AREA	123.5(W) X 43.0(H)	mm
CHARACTER SIZE	4.84(W) X 9.22(H)	mm
CHARACTER PITCH	6.0(W) X 9.75(H)	mm
DOT SIZE	0.92(W) X 1.1(H)	mm
DOT PITCH	0.98(W) X 1.16(H)	mm
APPROX WEIGHT	TBD	g
LCD TYPE	Blue STN, TRANSMISSIVE	
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	WHITE LED, SIDE	

# 3. Mechanical Specifications



\* Remark : General tolerance refers this model. ( $\pm 0.2$ mm)

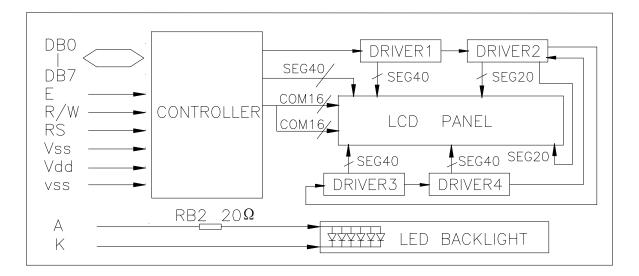
Easterntronic LCD Group

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- 4. Electrical Block Diagram
  - 4.1 Definition Pin

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(GND)
2	Vdd	Power Supply(+5V)
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	А	Power Supply For LED BL(+)
16	K	Power Supply For LED BL(-)

#### Electrical Block Diagram 4.2



#### Display Character Address Code 4.3

DISPLAY POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM	00	01	02	03	04	05	06	07	08	09	ОA	0B	0C	0D	0E	0F	10	11	12	13
	40		42																	
ADDRESS	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

### 5. Absolute Maximum Ratings

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	_	-0.3	Vdd +0.3	V

#### Electrical Maximum Ratings(Ta=25deg C) 5.1

#### 5.2 **Environmental Conditions**

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

# 6. ELECTRICAL SPECIFICATIONS

ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.4	4.7	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1.5	2.0	mA
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA
* Supply Voltage (LED)	V-bl	see note 1	2.9	3.1	3.3	V
*Supply Current (LED)	lf	see note 1	-	80	120	mA
*Deals femulated as meant(D/L)	Ife	I mseo pulse			2/0	
*Peak forward current(B/L)	lfp	10% Duty Cycle	-	-	360	mA
*Power dissipation(B/L)	Pd		-	-	510	mW

Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%6.1

Note 1: ( Backlight: Each side has 3 SMD LEDs and they are paralleled connection)

\*For operation above 25°C, the If, Ifp&Pd must be derated, the current derating is -2.16mA/ $^{\circ}$ C for DC drive and -5.16mA/ $^{\circ}$ C for pulse drive,the power dissipation is -6.912 mW / °C. The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature..

#### 6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V

# 6.2.1 Write mode

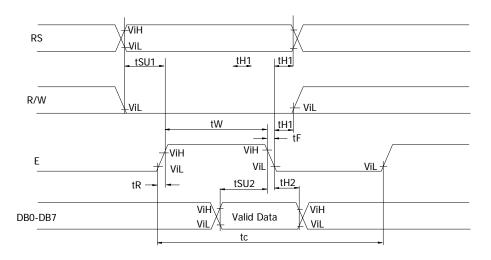
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

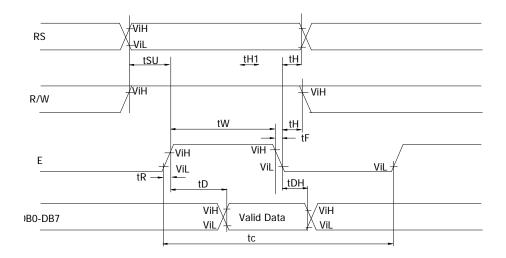
### 6.2.2 Read mode

ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

# 6.2.3 Timing Diagram

#### WRITE MODE TIMING DIAGRAM

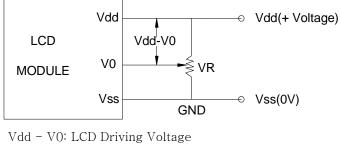




#### READ MODE TIMING DIAGRAM

### 7. Example of pwer spply

It is recommended to apply a potentiometer for the contrast adjust due to the tolerance of driving voltage and its temperature dependence.



VR: 10K - 20K

#### 8. Electro-Optical Characteristic

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	<b>25</b> ℃		12			Note1
Rise Time	tr	<b>25</b> ℃		160	240	ms	Note2
Fall Time	tf	<b>25</b> ℃		100	150	ms	note 2
	θ 1- θ 2	<b>25</b> ℃			60	DEG	Note 3
Viewing Angle	Ø1, Ø2	25 C	-40		40	DEG	Note 3
Frame Frequency	Ff	<b>25</b> ℃		70		Hz	note 2

Note(1): Contrast ratio is defined under the following condition:

CR= brightness of selected condition

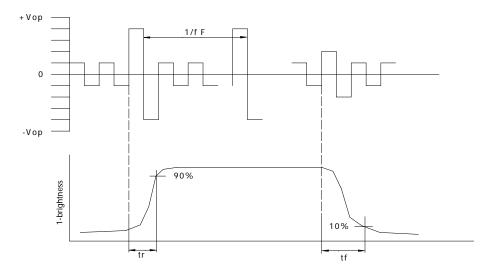
brightness of non-selected condition

(a). Temperature-----25C



- (b). Frame Frequency-----64Hz
- (c). Viewing angle------  $\theta = 0, \ \emptyset = 0$
- (d). Operating Voltage---4.7V

Note(2): definition of response time:

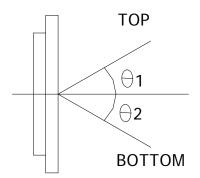


Condition:

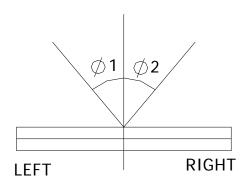
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0$ ,  $\emptyset = 0$
- (d). Operating Voltage---4.7V

Note(3): definition of view angle:

TOP-BOTTOM DIRECTION



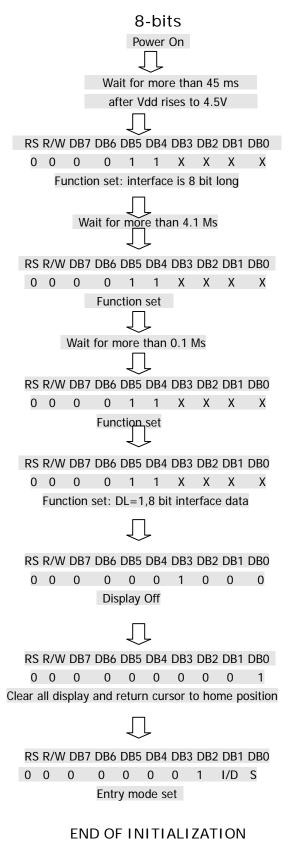
**RIGHT-LEFT DIRECTION** 



# 9. Instruction Table

Function	R	R	D	D	D	D	D	D	D	D	Description	Execu		
i dilotioni							В				•	Time*		
	Ŭ						3					(Max)		
Clear	0	0	_	_	_				_		Clears entire display and returns the cursor to			
Display	Ű	Ű	Ű	Ű	Ű	Ű	Ű	Ű	Ű	'	home position (address 0)	1.04113		
Return	0	Λ	0	0	0	Λ	0	0	1	v				
Home	0	0	0	0	0	U	0	0	1	^	Return the cursor to the home position. DD RAM 1.64n			
поше											contents remain unchanged. Set DD RAM address			
Entry (	0	0	0	0	0	0	0	1	1	c	to zero.	10 11 5		
Entry	U	0	U	0	0	0	0	I	,	2	Set cursor moving direction and enable the			
mode									/		shift of the display. These operations are			
set									D		performed during data write/read of DD RAM/CG			
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:			
	-	_	_	_	_	_	_	_	_	_	whole display shift when data is written.	10.0		
Display	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor(C) and blinking of cursor(B)	40 µ S		
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.			
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;			
											B=0, Blink OFF.			
	0	0	0	0	0	1	S	R	Х	Х	Move the cursor and shift the display without	40 µ S		
Display							/	/			changing DDRAM contents. S/C=1: Display Shift;			
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;			
											R/L=0:shift to left.			
Function	0	0	0	0	1	D	Ν	F	Х	Х	Set interface data length (DL), number of display	40 µ S		
Set						L					lines (N) and character font (F).DL=1: 8 bits;			
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. $F=1$ :			
											5X11 dots; F=0: 5X7 dots.			
Set CG	0	0	0	1			AC	CG	i		Set CG RAM address. CG RAM data is sent and	40 µ S		
RAM add											received after this setting.			
Set DD	0	0	1			A	D	D			Set DD RAM address. DD RAM data is sent and	40 µ S		
RAM Add											received after this setting.			
Read BF	0	1	В			1	AC	;			Read BUSY FLAG (BF) and the contents of the	0 µ S		
& Addr			F								address counter. BF=1: internal operation; BF=0:			
											can accept instruction.			
Write Data	1	0	١	N	RI.	TE	E	)A	TA	ł	Write data into DD RAM or CG RAM.	40		
to RAM												μ <b>S</b> **		
Read Data	1	0		RI	ΕA	D	D	A	ГA		Read data from DD RAM or CG RAM.	40		
from RAM												μ <b>S**</b>		

#### **10.Initialization By Instruction**



4-bits Power On Wait for more than 45 mS after Vdd rises to 4.5V RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 Function set: DL=1,8 bit interface data. Wait for more than 4.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 DL=1,8 bit interface data Wait for more than 0.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 0 0 N F X X Function set: DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 1 0 0 0 Display Off ٦Ļ RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 0 1 Function set: DL=0.4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 1 I/D S Entry mode set END OF INITIALIZATION



# 11.Software Examples

#### 8-BIT OPERATION 8 characters X 2 lines

Function	RS R	W D7	' D6	D5	D4	D3	D2	D1	D0	DISPLAY	DESCRIPTION
Power on delay			-	-	-	-			-		Initialization. No display appears.
Function set	0 0	0	0	1	1	0	0	Х	Х		Sets 8-bit operation, 2-line display and 5*7
											dots character font.
Display OFF	0 0	0	0	0	0	1	0	0	0		Turn off display.
Display ON	0 0	0	0	0	0	1	1	1	0		Turn on display and cursor.
Entry Mode set	0 0	0	0	0	0	0	1	1	0		Set mode to increment the address by one
											and to shift the cursor to the right, at the
											time of write to the DD/CG RAM. Display
											is not shifted.
Write data to	1 0	0	1	0	0	1	1	1	1	0	Write "O". Cursor incremented by one and
CG/DD RAM											shift to right.
Write data to	1 0	0	1	0	1	0	0	1	0	<u>OR</u>	Write "R". Cursor incremented by one and
CG/DD RAM											shift to right
Write data to										ORIENT	Write "I" "E" "N" "T".
CG/DD RAM											
Set DDRAM	0 0	1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the cursor is
address											positioned at the head of the Second line
Write data to						•				ORIENT	Write "D" "S".
CG/DD RAM										DS	
Cursor or display	0 0	0	0	0	1	0	0	Х	Х	ORIENT	Shift only the cursor position to the left.
shift										DS	
Write data to				•						ORIENT	Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM										DISPLAY	

#### 4-bit operation (4-bits 1 line)

0 0 0 0 0 0	1	-		as 8-bits by initialization,a nd Only this instruction completes with one write. Sets 4 -bit operation, 1-line display and 5*7 dot character
0 0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8-bits by initialization,a nd Only this instruction completes with one write. Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be
		-		
				changed hence after.)
0 0 1 1			_	Turn on display and cursor.
			_	Turn on display and cursor.
		0 1		Write "O". Curaor incrementer by one and shift to right.
	0 0 0 1 0 1	0 0 0 0 1 1 0 1 0	0     0     0     0       0     1     1     0       0     1     0     0       1     1     1     1	0       0       0       0

# 12. Quality units

### 12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

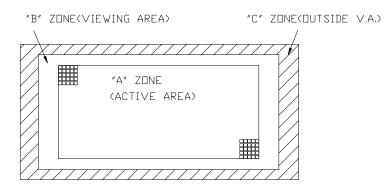
12.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

# 12.3 Definition

### 12.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



# 12.3.2 Definition of size

Large size(L):  $1 \sim 6 \text{ pcs LCD}$  screens are cut out of from each  $14" \times 16"$  mother glass. Middle size(M):  $7 \sim 50$  pcs LCD screens are cut out of from each  $14" \times 16"$ mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each  $14"\times16"$ mother glass.

12.4 Quality Specification

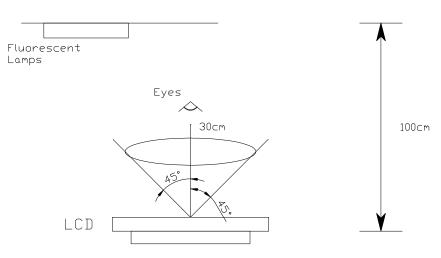
# 12.4.1 Conditions of Cosmetic Inspection

12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 $\pm$ 5°C. Ambient humidity:  $65 \pm 20\%$ RH Ambient Luminance: 40-watt fluorescent lamp. An appearance test should be conducted by human sight at approximately 30 cm distance



from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

# 12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument



- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

# 12.4.5 Inspection quality criterion

### 12.4.5.1 LCD panel part

Classify	Item	Description of defects	Inspect	ion criterion	Drawing specification
Major defect	1.Non-display	Product no function	No	ot accept	
	2.LCD with wrong view direction`	Difference in Spec.	Not accept		
	3.Segment missing	Part or all pattern do not light up	No	ot accept	
	4.Occur high current	Current exceed designed value	No	ot accept	
	5. LC leakage	LC does not fulfill the glass cell	No	ot accept	
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	According to dimensions noted in the specification		
	7.Wrong type applied	Wrong polarizer attachment	No	ot accept	
		Pin attached wrong type applied	No	ot accept	
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not accept		
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to next dot)	



			0.10 <a≤0.15 B ≤ 0.10</a≤0.15 	1 pc / dot(only segment)or less 2 pcs / cell or less (Should not be connected to next dot)	
Minor defect	10.Pinholes	Black spot/white spot at activated state	distance and under e 2. Middle si Diameter(mm $\Phi \le 0.15$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.35$ $\Phi > 0.35$ 3. Small siz Diameter(mm $\Phi \le 0.15$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $\Phi > 0.30$ 4. For the c if the are than or ec lattice's 5. Only allo one segm 6. The n allowed pinholes i <b>Remark</b> product in neg TN, STN and driving voltag should be less $\le 0.2$ ). If the dr 0.3V th voltage, it car	a't be found at 1m d will not enlarge lectronic test ze LCD a) Accept QTY Not count 3 1 0 e LCD a) Accept QTY 5 Not count 2 1 0 kot count 2 kot count 2 k count 2 kount 2	$\Phi = (X+Y)/2$

11.Blemishes	Black spot/dust	Positive panel:	+
and foreign	on	1.A zone	
matters	LCD(non-display	- Large size LCD	
	)	Accept if can't find at 1m	
	,	distance and will not enlarge	$\wedge$
		under electronic test:	$\Phi = (X+Y)/2$
		-Middle size LCD	× /
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 3	
		$0.25 < \Phi \le 0.35$ 1	
		$\Phi \! > \! 0.35$ 0	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 2	
		$0.25 < \Phi \le 0.30$ 1	
		$\Phi \! > \! 0.30$ 0	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \leq$ 0.15 Not count	
		$0.15 < \Phi \le 0.30$ 4	
		$0.30 < \Phi \le 0.50$ 1	
		$\Phi \! > \! 0.50$ 0	
		-Middle&small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \leq$ 0.15 Not count	
		$0.15 < \Phi \le 0.25$ 3	
		$\Phi \! > \! 0.25$ 0	
		2. B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		No count	
		The nearest diatance allowed	
		between two black spot is	
		20mm	



10 01 1		<b>D</b> 11	
12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	
scratches	surface.And	- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		0.02< W≤ 0.03,L ≤4 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4 = 0$	
		$0.03 < W \le 0.05, L > 3$ 0	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$ 1	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 2$ 0	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Nogotivo popol:	
		Negative panel: 1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY $W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2 $0.02 < W \le 0.03, L > 5$ 0	
		$\begin{array}{llllllllllllllllllllllllllllllllllll$	
		W>0.05 As the spot criteria.	



				1
			-Middle size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. -Small size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.05, L \ge 2$ 0 W > 0.05 As the spot criteria. <b>2. B zone</b> 1.5 times of acceptable largest diameter size of Zone A <b>3.C zone</b> Not count The nearest diatance allowed between two defects is 20mm	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	



		r					
Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink	Accept i	f the thick	c or thir	n part is	
		pattern/line	less than	n equal to	25% s	egment	
		jagged	width, o	r accordi	ng to th	ne limit	
			specimer		-		
		17.3 Light	When	activated	with	current	
		leakage	white lig	ht appears	s in the	osition	
				le or scra			
			-	misalignr			
				nhole spec			
			·· ··· ··	F			
		17.4 Ink printing	Reject if	the thick	or thin	in more	
		pattern/line	than $1/2$				$\downarrow$ $\vee$
		uneven	Reject w	hen W1-V	V2≤1/3V	V	
			5				W1 W2
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	g	defect:	`
defect		or foreign	oxidized	,damage(i	ncludin	g pins	
		material on		damaged)			
		terminal legs		om glass			
		E C	legs.Not	-			
		18.2 Pin		ng to the s	pecifica	tion	
		deviation over		8	<b>L</b>		
		tolerance					
Mintor	19. Chipped	19.1 Chip in	a	b	с	accept	
defect	glass on	lead contact	u	U	Ũ	QTY	
dereet	comer	area.	a≤5mm	b≤W	c≤T	<b>Q</b> 11	
	conter	ureu.	L>5m	0.2.00	0.51	3	
						5	ITO
			m a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			a∖L	U≤w	C>1	5	
			L<5m				
							D A A
			m				
		19.2 Others	Not exc	ceed $1/2$			¥
		17.2 Others	width of		c≤T	3	
				Jour	V-1		



					T	1			
Mintor	20. Glass	chip on edge	а	b	с	accept			
defect						QTY			
			a≤5mm	Not	c≤T	3			
			exceed						
				1/2					
				width					
		Ι		of seal					
	21. Clipped	21.1Glass chip	а	b	с	accept	ITD		
Mintor	electrode pad	on ITO edge				QTY			
defect			a≤4mm	b≤W/4	C≤T	3			
			(and						
			not						
			exceed						
			4 ITO						
			termina						
			1						
		21.2 Glass chip	а	b	c	accept	۵ پ پ		
		on ITO back		_		QTY			
			a≤5mm	b≤W/3	c≤T	3			
							KITE		
							$\vee$		
Minter		Estended en els	1.						
Mintor	22. Mashariaal	Extended crack	b		accept QTY				
defect	Mechanical	inspector shall							
	damage	attempt to	b≤W/4		2				
		remove the chip							
		with					b		
		tweezers,re-eval uate if the					b		
		remaining defect is still a crack or							
Mintor	22 Cl	a chip ass cracks	Not acce	nt					
defect	23.01	155 UIAUNS	not acce	μ					
Remark				A 1 1		4 20	1 11 1		
		etween any 2 defec	ets(spot,dir	t) should	more	than 20m	m, and max. allowed		
	TY in total:	Church 7 D.C	1						
Large si	Large size LCD: Zone A $\leq$ 5/unit, Zone B $\leq$ 5/unit;								

Middle size LCD: Zone A $\leq$  3/unit, Zone B $\leq$  3/unit;

Small size LCD: Zone A $\leq$  2/unit, Zone B $\leq$  2/unit;



# 12.4.5.2 Other part

The inspection	specification	as following list:
The mopeetion	specification	as rono ning noti

NO.	Items	Criterion of defects	AQL			
1	Backlight	<ol> <li>Lumination source flickers.</li> <li>Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight.</li> </ol>				
		3. Not allow unlighted on backlight.				
		4. Colour and luminance of backlight should correspond its specification.	Major			
2	PCB,COB	1.COB seal may not have pinholes larger than0.2mm or contamination.				
		2.COB seal surface may not have pinholes through to the IC.	Minor			
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major			
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor			
		5.No oxidation or contamination on PCB connector.	Minor			
		6.Parts on PCB should correspond the characteristic, and not	Major			
		allow wrong parts, missing parts or additional parts.				
		7.The jumper on the PCB should correspond to the characteristic.	Minor			
		8. The solder which gets on bezel, LED pad, zebra pad or screw hole pad should be smoothed down.	Major			
		1. No unmelted solder pastes on the PCB.	Minor			
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor			
		3. No short circuits in components on PCB.	Minor			
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor			
		2. No solder residue or solder balls on product.	Minor			
		3. The IC on TCP may not be damaged.	Major			
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor			
		5. Packing method correspond the specification.	Major			
		6. Dimension and structure correspond the specification sheet.	Major			
		7. No dirt and break on the heat seal.	Major			

# 12.5 Reliability

Item	Condition	Criterion						
High temperature operation	$+70^{\circ}\text{C}\pm2^{\circ}\text{C}$ , 8 ho	Durs						
Low temperature operation	$-20^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , 8 ho	1.Total current consumption						
Humidity	Operation	$40^{\circ}$ C $\pm 2^{\circ}$ C ,93% $\pm 2$ % RH,8 hours	should be below double of initial					
	Storage	40 °C ± 2 °C ,93% ± 2%RH, 24 hours	value. 2.Cosmetic defects					
High temperature storage	$+80^{\circ}\text{C}\pm2^{\circ}\text{C}$ , 10 H	should not be happened						
Low temperature storage	$-30^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , 10 h							
Thermal shock	-20°C∼+70°C							
storage	60min~60min, 5 cy							
Vibration test	Amplitude:0.7~1.0 in each direction(X							
Shock test		To be measured after dropping from 60cm or						
	80cm high on the c							
	state.(weight≥15k							
	Weight <15Kg,dro							
	G B	Dropping method corner dropping A corner: once Edge dropping B,C,D edge: once B0cm ELF,G face: once						
Remark: The function test shall be conducted after 4 hours storage at the normal								
temperature and humidity after removed from the test chamber.								

The LCD module shall not fail the following reliability test.

# 13. character Pattern

# NO.7066-0B

	000-	00									-					
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	0															
0111	(8)															
1000	(1)															
1001	(2)															
1010	3															
1011	(4)															
1100	(5)															
1101	(6)															
1110	Ø															
1111	(8)															

#### 14.Precaution For Using LCM

#### 1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The followina precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

Wipe off saliva or water drops immediately. (3). Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.

(5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280  $^\circ\!\mathrm{C}\pm10^\circ\!\mathrm{C}$ 

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

Response time increases with decrease in (3). temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

15. Declaration of conformity regarding the limitation of dangerous substances

# 深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2004C-D-BSXTSWN-190 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

•Lead

• Mercury

● Cadmium

•Hexavalant chromium

Polybrominated biphenyls

• Polybrominated diphenylethers

And to the annex which points out the exempted implementations  $\Box$  To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• 0ils containing polychlorinated biphenyl

Asbestos

• Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO ., LTD.

Issued on April 2, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.